

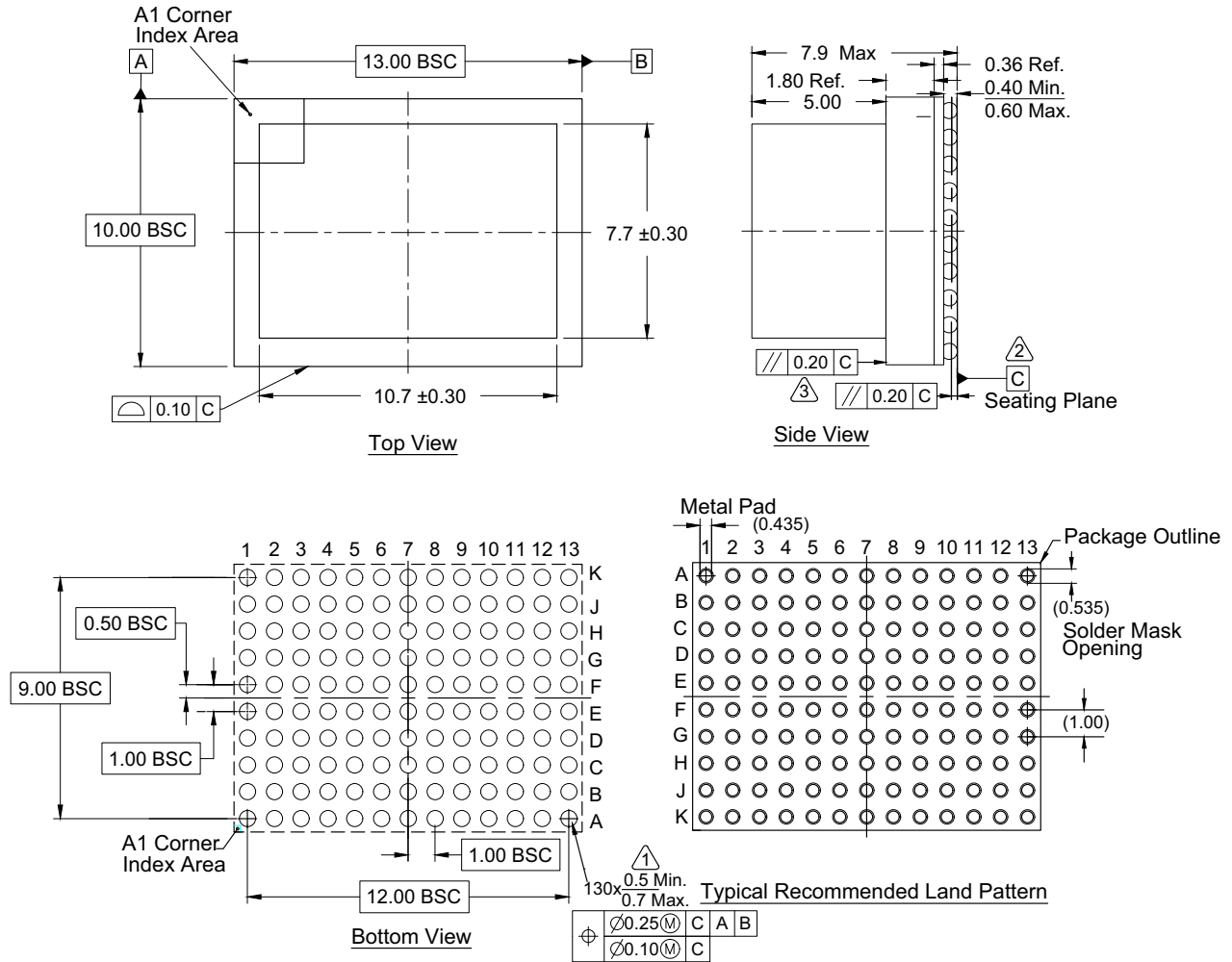
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

V130.10x13

130 Ball Plastic Ball Grid Array Package (POP)

Rev 1, 9/2023



### Notes:

- ① Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
- ② Datum C (seating plane) is defined by the spherical crowns of the solder balls.
- ③ Parallelism measurement shall exclude any effect of the mark on the top surface of the package.
4. All dimensions and tolerances conform to ASME Y14.5M.
5. Units: mm